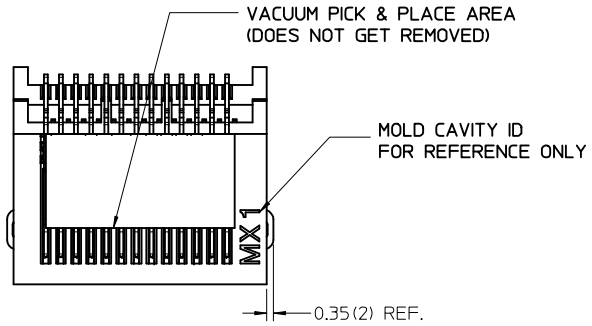
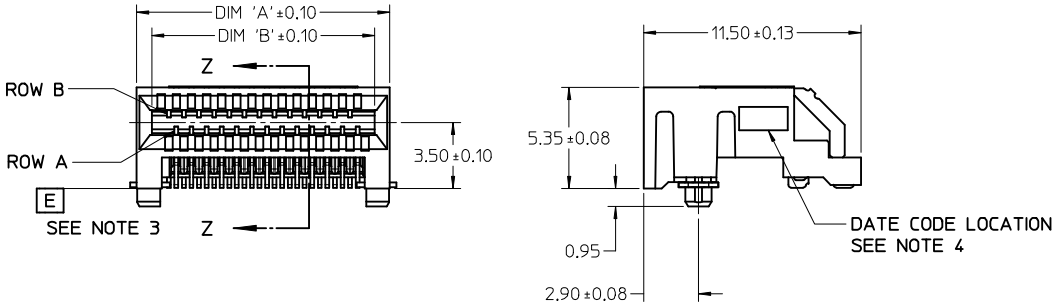
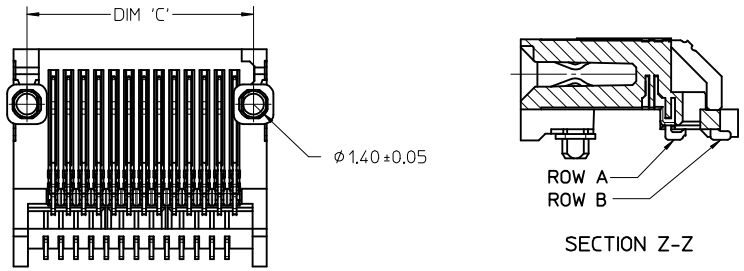
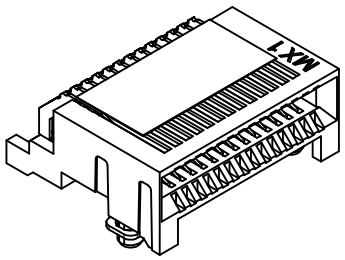






SECTION Z-Z



CIRCUIT SIZE	ITEM NUMBER	PLATING OPTION	DIM 'A'	DIM 'B'	DIM 'C'
26	75586-0101	OPTION 1	13.40	11.80	12.00
26	75586-0102	OPTION 2	13.40	11.80	12.00
38	75586-0103	OPTION 1	18.20	16.60	16.80
38	75586-0104	OPTION 2	18.20	16.60	16.80
68	75586-0105	OPTION 1	30.20	28.60	28.80
68	75586-0106	OPTION 2	30.20	28.60	28.80

NOTES

1. MATERIAL:
   HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED, UL 94V-0, BLACK
   TERMINALS - COPPER ALLOY
2. PLATING:
   OPTION 1
   CONTACT AREA - 0.38 µm MIN GOLD OVER 2.54 µm MIN NICKEL
   SOLDER FOOT AREA - 2.54 - 5.09 µm TIN OVER 1.27 µm MIN NICKEL.
   OPTION 2
   CONTACT AREA - 0.76 µm MIN GOLD OVER 2.54 µm NICKEL
   SOLDER AREA - 2.54 -5.09 µm TIN OVER 1.27 µm MIN NICKEL
3. TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/.004 MEASURED FROM FRONT HOUSING STAND OFF (DATUM E)
4. DATE CODE: 4 DIGIT (3 DIGIT DATE, 1 DIGIT YEAR)
5. CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1
6. TO BE USED WITH EXTERNAL CABLES (74546 & 74547 SERIES) AND GUIDE FRAMES (74540 & 74548 SERIES)
7. TESTER/ANALYZER CABLES AVAILABLE (74557 & 74558 SERIES)
8. PACKAGED PER PACKAGING SPECIFICATION: PK-75586-002
9. CONFORMS TO PRODUCT SPECIFICATION: PS-75586-001
10. THIS PART CONFORMS TO CLASS C REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

REV NOTE 2
EC NO: UCP2015-0453 2014/07/31
DRWN:KBINGHAM 2014/08/01
CHKD:TMCCLELLAND 2014/08/01
APPR:TMCCLELL 2014/08/01
DESCRIPTION
REV
C2

QUALITY SYMBOLS
=0
=0
=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.13	± ---
1 PLACE	± 0.25	± ---
0 PLACE	±	±

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 5:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

	NAME	DATE
DRAWN BY	KLANG	12/06/2006
CHECKED BY	JSWENSON	12/06/2006
APPROVED BY	MBANAKIS	12/06/2006

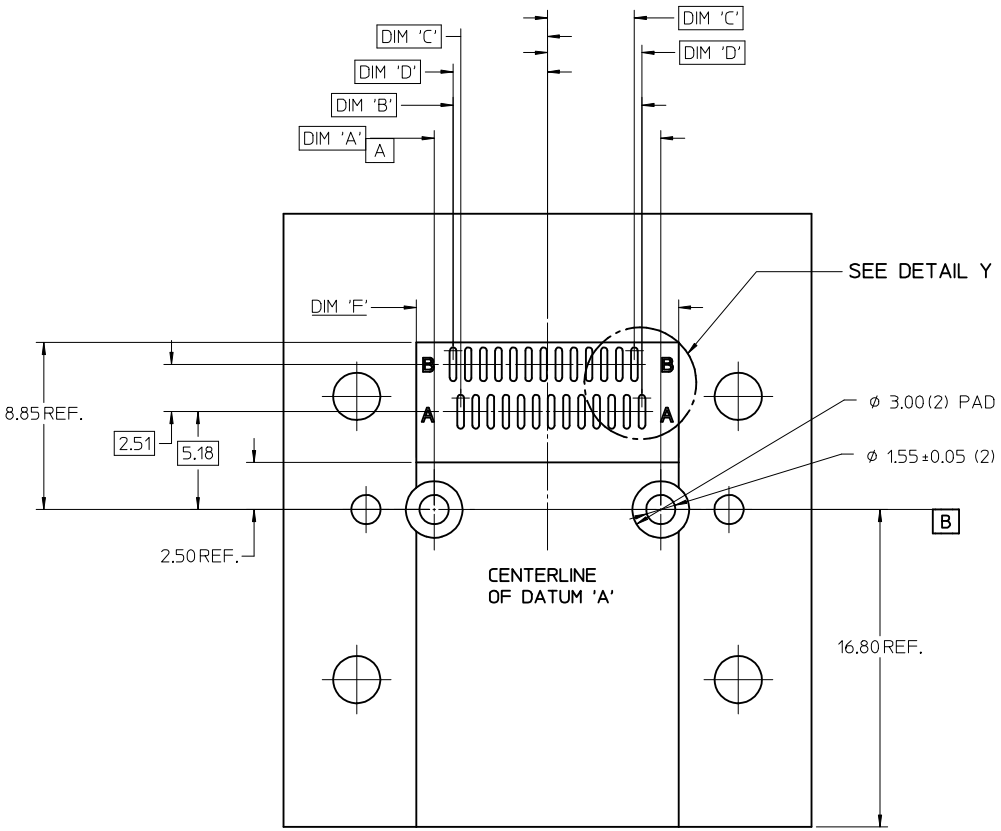
TITLE: IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING

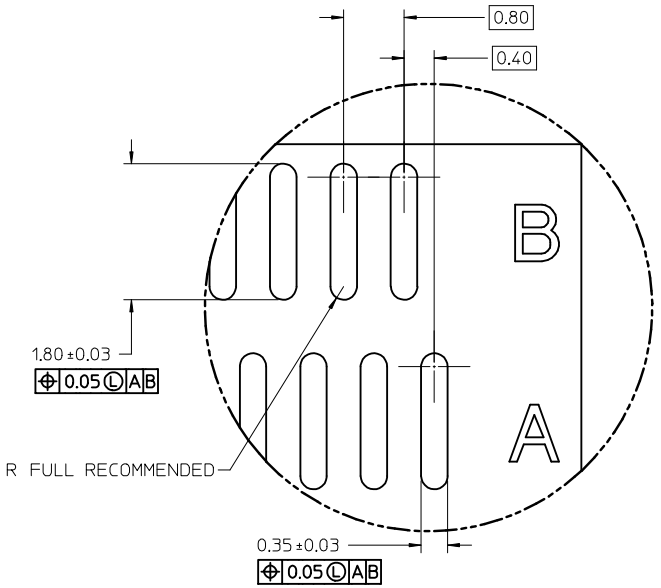
molex

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-75586-005
SHEET NO.: 1 OF 6
SIZE: C

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

MOTHERBOARD FOOTPRINT RECOMMENDATION





DETAIL Y
SCALE 20:1

NOTES:
1. SEE 74540 OR 74548 SERIES FOR GUIDE FRAME FOOT PRINT AND KEEP OUT AREA.

CIRCUIT SIZE	TERM/SIDE 'N'	DIM 'A' PEG TO PEG	DIM 'B' FIRST PAD TO LAST PAD	DIM 'C' CENTERLINE TO PAD	DIM 'D' CENTERLINE TO PAD	DIM 'E' MODULE BOARD WIDTH	DIM 'F' CONNECTOR WIDTH
26	13	12.00	10.00	4.60	5.00	11.60	13.90
38	19	16.80	14.80	7.00	7.40	16.40	18.70
68	34	28.80	26.80	13.00	13.40	28.40	30.70

SEE SHEET 1
EC NO: UCP2015-0453 2014/07/31
DRWN:KBINGHAM 2014/08/01
CH'KD:TMCCLELLAND 2014/08/01
APPR:TMCCLELL 2014/08/01
DESCRIPTION
C2
REV

QUALITY SYMBOLS
=0
=0
=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.13	± ---
1 PLACE	± 0.25	± ---
0 PLACE	±	±

ANGULAR ±1/2°
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

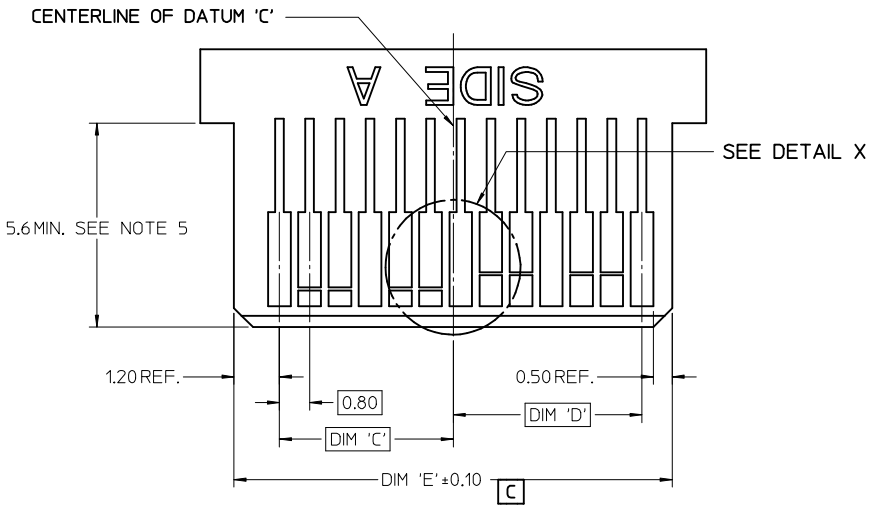
DIMENSION STYLE: MM ONLY
SCALE: 10:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

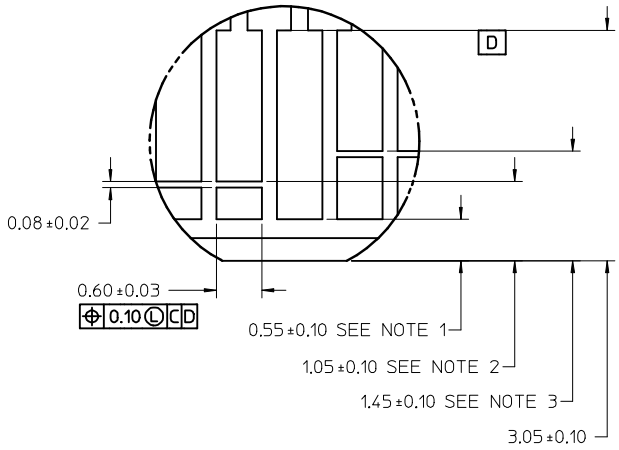
DRAWN BY: KLANG DATE: 12/06/2006
CHECKED BY: JSWENSON DATE: 12/06/2006
APPROVED BY: MBANAKIS DATE: 12/06/2006
MATERIAL NO.: SEE CHART
SIZE: C

TITLE: IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING
molex
DOCUMENT NO.: SD-75586-005
SHEET NO.: 2 OF 6

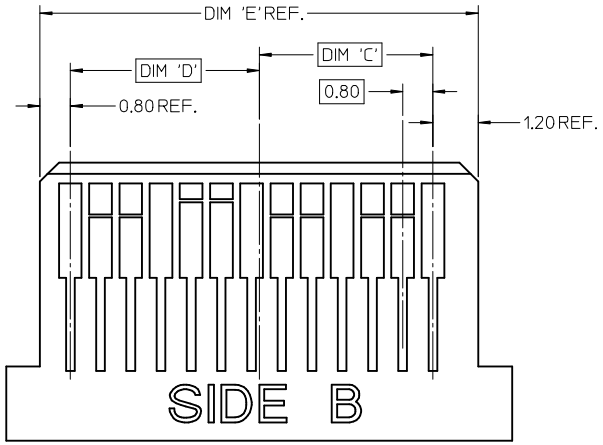
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

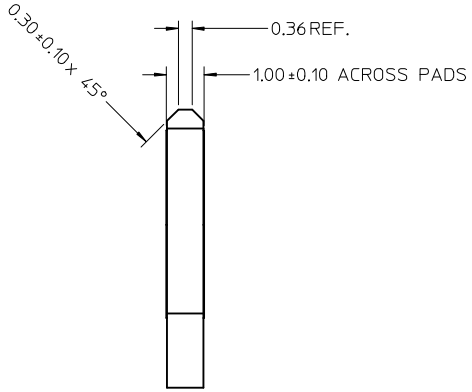
MODULE BOARD FOOTPRINT RECOMMENDATION





DETAIL X
SCALE 20:1





NOTES:
1. PAD CONFIGURATION FOR FIRST MATE.
2. PAD CONFIGURATION FOR SECOND MATE.
3. PAD CONFIGURATION FOR THIRD MATE (HIGH SPEED SIGNALS).
4. FOR PIN ASSIGNMENTS AND MATING SEQUENCE (1ST, 2ND, 3RD), SEE APPLICABLE SPECIFICATION.
5. MINIMUM STEP REQUIRED IF PCB MADE WIDER THAN CARD TONGUE.

CIRCUIT SIZE	TERM/SIDE 'N'	DIM 'C' CENTERLINE TO PAD	DIM 'D' CENTERLINE TO PAD	DIM 'E' MODULE BOARD WIDTH
26	13	4.60	5.00	11.60
38	19	7.00	7.40	16.40
68	34	13.00	13.40	28.40

SEE SHEET 1
EC NO: UCP2015-0453 2014/07/31
DRWN: KBINGHAM 2014/08/01
CHKD: TMCCLELLAND 2014/08/01
APPR: TMCCLELL
DESCRIPTION
C2
REV

QUALITY SYMBOLS
F1 =0
F2 =0
F3 =0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.13	± ---
1 PLACE	± 0.25	± ---
0 PLACE	±	±

ANGULAR ±1/2°
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 10:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: KLANG DATE: 12/06/2006
CHECKED BY: JSWENSON DATE: 12/06/2006
APPROVED BY: MBANAKIS DATE: 12/06/2006

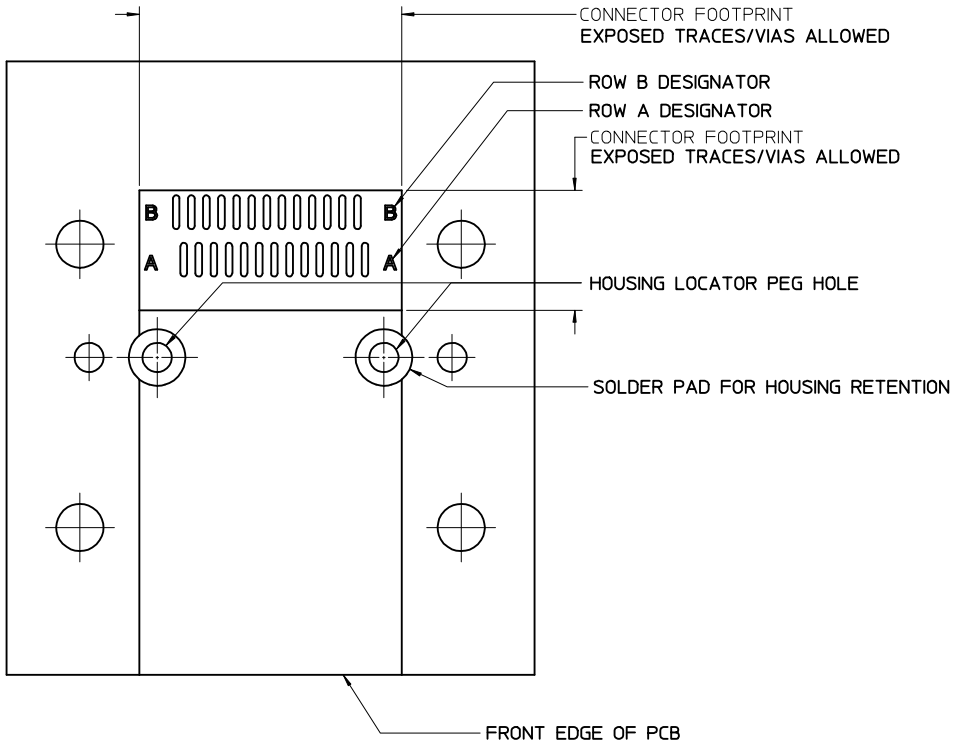
TITLE: IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING

molex

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-75586-005
SHEET NO.: 3 OF 6
SIZE: C

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

CONNECTOR FOOTPRINT ZONE IDENTIFICATION



SEE SHEET 1
EC NO: UCP2015-0453 2014/07/31
DRWN:KBINGHAM 2014/08/01
CHKD:TMCCLELLAND 2014/08/01
APPR:TMCCLELL 2014/08/01
DESCRIPTION
C2
REV

QUALITY SYMBOLS
=0
=0
=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.13	± ---
1 PLACE	± 0.25	± ---
0 PLACE	±	±

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 5:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

		DATE
DRAWN BY	KLANG	12/06/2006
CHECKED BY	JSWENSON	12/06/2006
APPROVED BY	MBANAKIS	12/06/2006

TITLE: IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING

molex

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-75586-005
SHEET NO.: 4 OF 6
SIZE: C

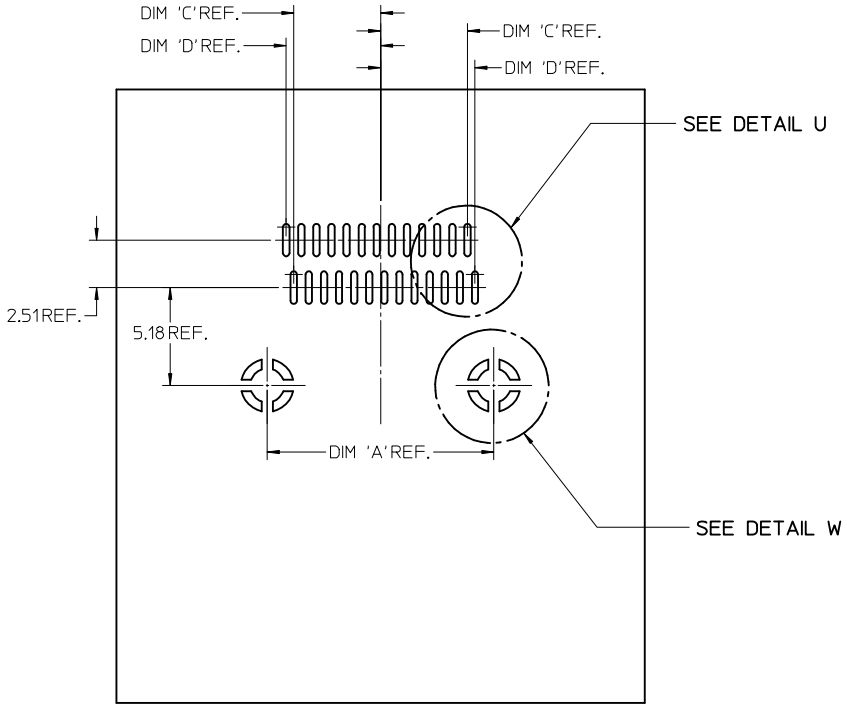
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

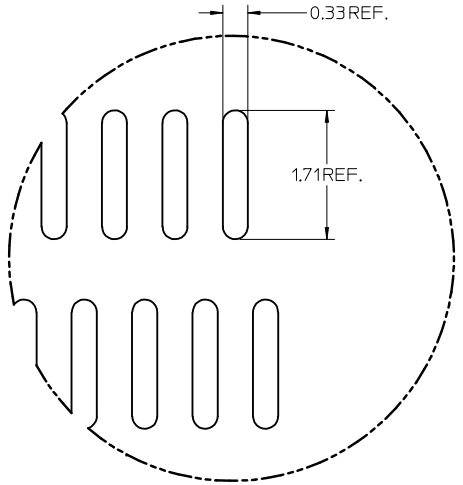
NOTES:

1. STENCIL RECOMMENDATION IS A GUIDELINE ONLY.
2. MANUFACTURING PROCESS PARAMETERS WILL DEFINE THE ACTUAL STENCIL DEFINITION.
3. RECOMMENDED STENCIL THICKNESS IS 0.13MM.

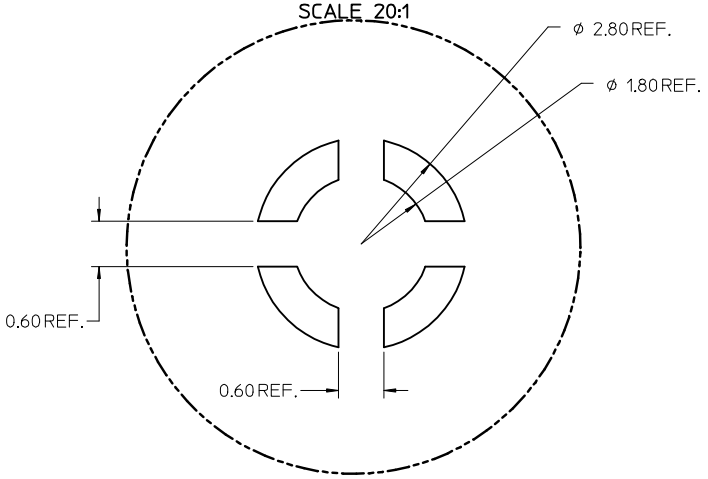
SOLDER STENCIL RECOMMENDATION

SOLDER FOOT: ~90% OF PAD
SOLDER RING: ~45% OF PAD





DETAIL U
SCALE 20:1



DETAIL W
SCALE 20:1

CIRCUIT SIZE	TERM/SIDE 'N'	DIM 'A' (PEG TO PEG)	DIM 'C' (CENTERLINE TO PAD)	DIM 'D' (CENTERLINE TO PAD)
26	13	12.00	4.60	5.00
38	19	16.80	7.00	7.40
68	34	26.80	13.00	13.40

SEE SHEET 1
EC NO: UCP2015-0453 2014/07/31
DRWN: KBINGHAM 2014/08/01
CHKD: TMCCLELLAND 2014/08/01
APPR: TMCCLELL
DESCRIPTION
C2
REV

QUALITY SYMBOLS

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.13	± ---
1 PLACE	± 0.25	± ---
0 PLACE	±	±

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 5:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

		DATE
DRAWN BY	KLANG	12/06/2006
CHECKED BY	JSWENSON	12/06/2006
APPROVED BY	MBANAKIS	12/06/2006

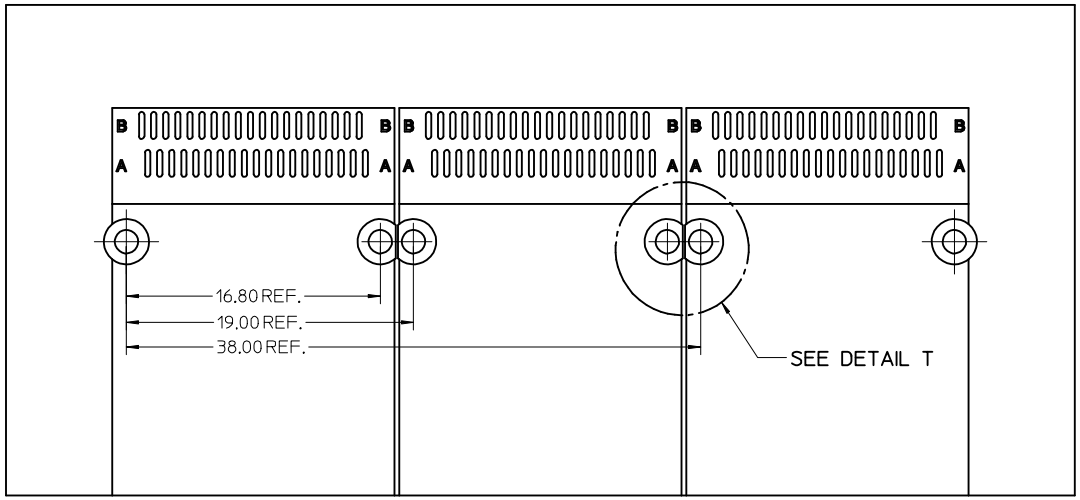
TITLE: IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING

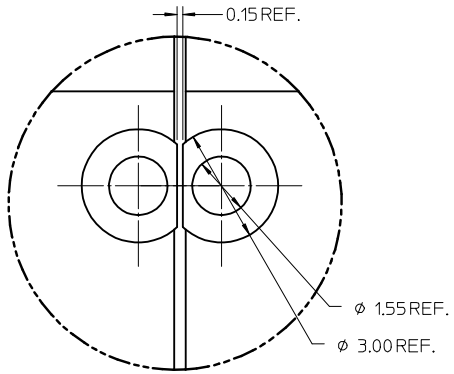
molex

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-75586-005
SHEET NO.: 5 OF 6
SIZE: C

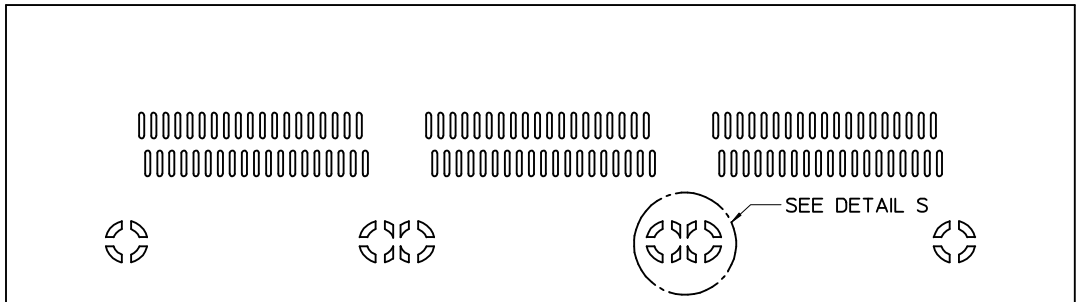
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

38 CIRCUIT GANGED ON 19.00 mm CENTERLINE



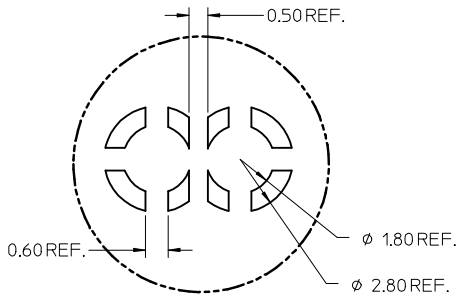


DETAIL T
SCALE 10:1



SOLDER STENCIL RECOMMENDATION
GANGED ON 17.00 mm PITCH

SOLDER FOOT: ~90% OF PAD
SOLDER RING: ~45% OF PAD



DETAIL S
SCALE 10:1

NOTES:

1. STENCIL RECOMMENDATION IS A GUIDELINE ONLY.
2. MANUFACTURING PROCESS PARAMETERS WILL DEFINE THE ACTUAL STENCIL DEFINITION.
3. RECOMMENDED STENCIL THICKNESS IS 0.13MM.

SEE SHEET 1
EC NO: UCP2015-0453 2014/07/31
DRWN:KBINGHAM 2014/08/01
CHKD:TMCCLELLAND 2014/08/01
APPR:TMCCLELL
DESCRIPTION
C2
REV

QUALITY SYMBOLS

GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.13	± ---
1 PLACE	± 0.25	± ---
0 PLACE	±	±
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	4:1
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	KLANG 12/06/2006
CHECKED BY	JSWENSON 12/06/2006
APPROVED BY	MBANAKIS 12/06/2006
MATERIAL NO.	SEE CHART
TITLE	IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING
DOCUMENT NO.	SD-75586-005
SHEET NO.	6 OF 6
SIZE	C

molex

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION